

# SOT1688-1(DD)

HLQFN16; plastic, thermal enhanced low profile quad flat non-leaded package, dimple wettable flank; 16 terminals; 0.8 mm pitch; 4 mm x 4 mm x 1.45 mm body

9 December 2020

Package information

## 1 Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HLQFN16
<b>Package type industry code</b>	HLQFN16
<b>Package style descriptive code</b>	HLQFN (thermal enhanced low profile quad flatpack; no leads)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	11-09-2019
<b>Manufacturer package code</b>	98ASA01254D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	3.9	4	4.1	mm
package width	3.9	4	4.1	mm
seated height	1.4	1.45	1.5	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	16	-	



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2 Package outline

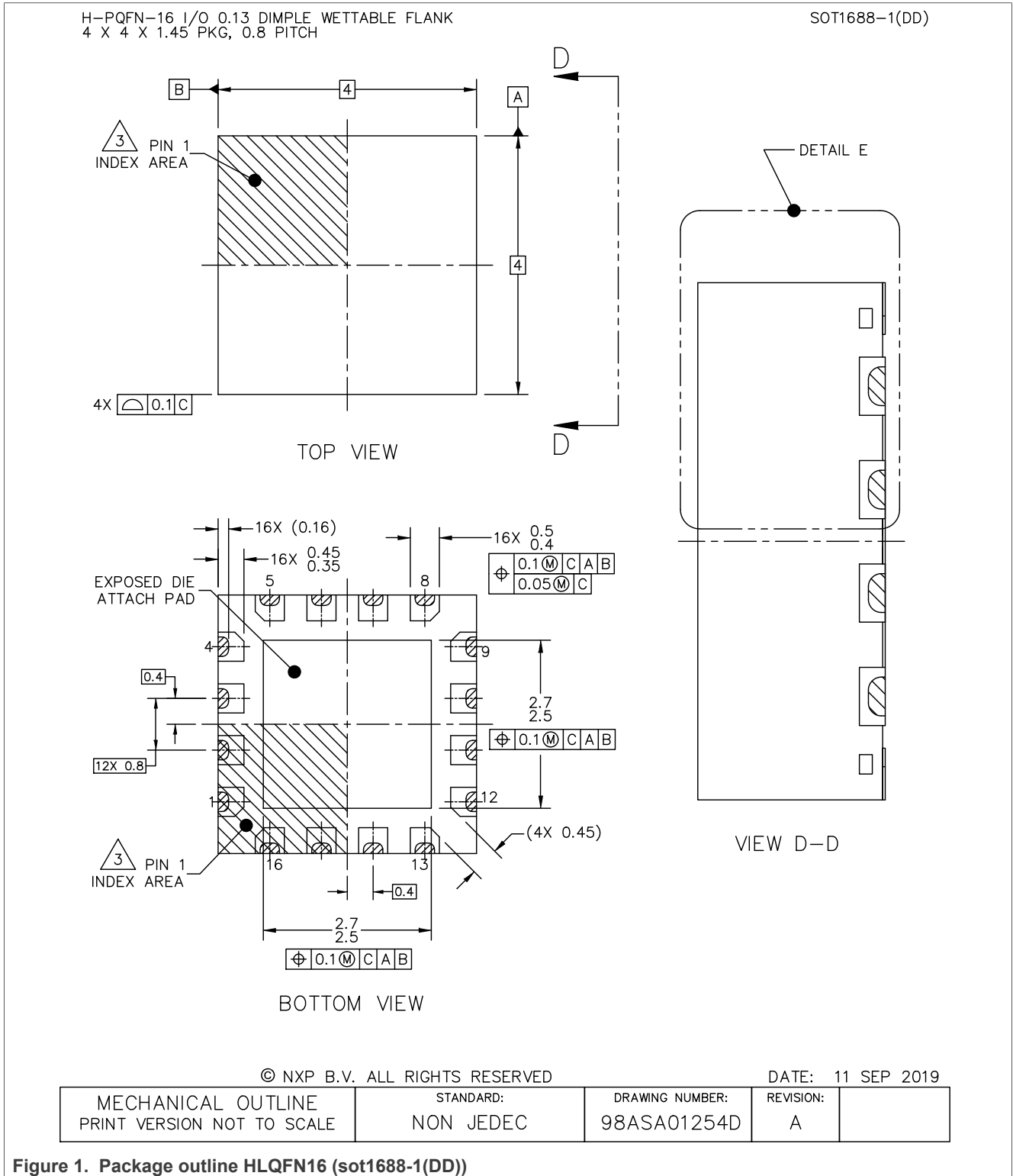
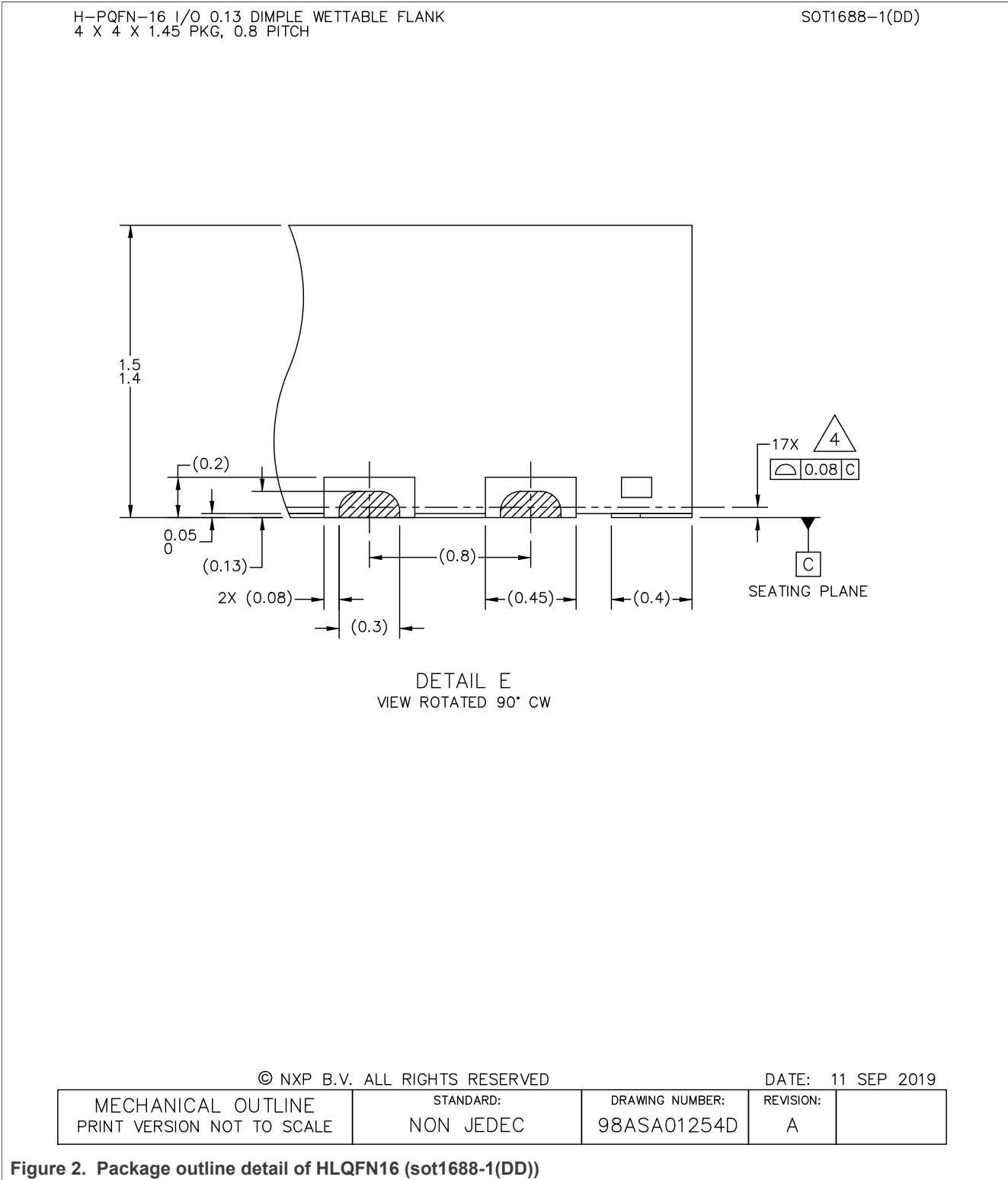


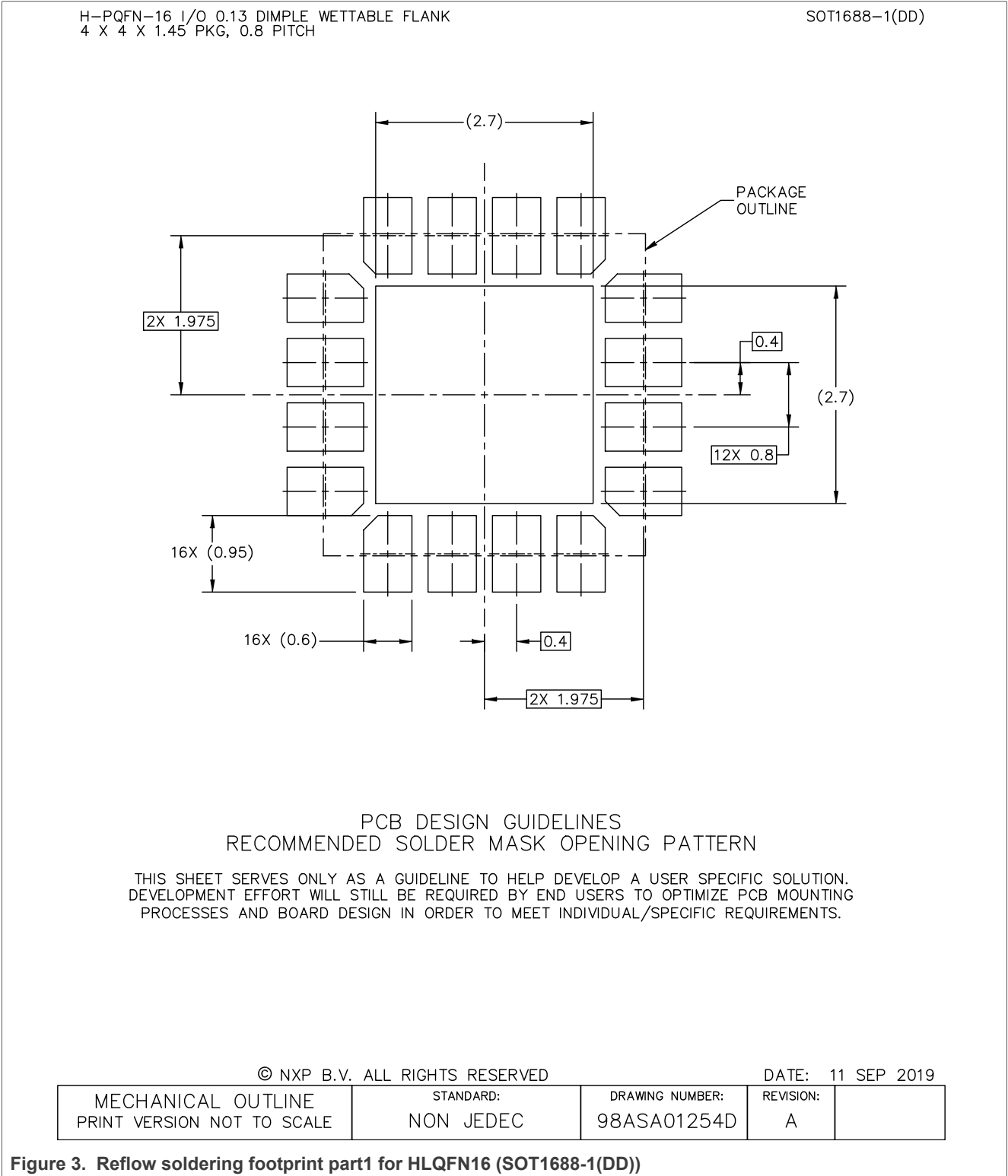
Figure 1. Package outline HLQFN16 (sot1688-1(DD))

HLQFN16; plastic, thermal enhanced low profile quad flat non-leaded package, dimple wettable flank; 16 terminals; 0.8 mm pitch; 4 mm x 4 mm x 1.45 mm body



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3 Soldering



HLQFN16; plastic, thermal enhanced low profile quad flat non-leded package, dimple wettable flank; 16 terminals; 0.8 mm pitch; 4 mm x 4 mm x 1.45 mm body

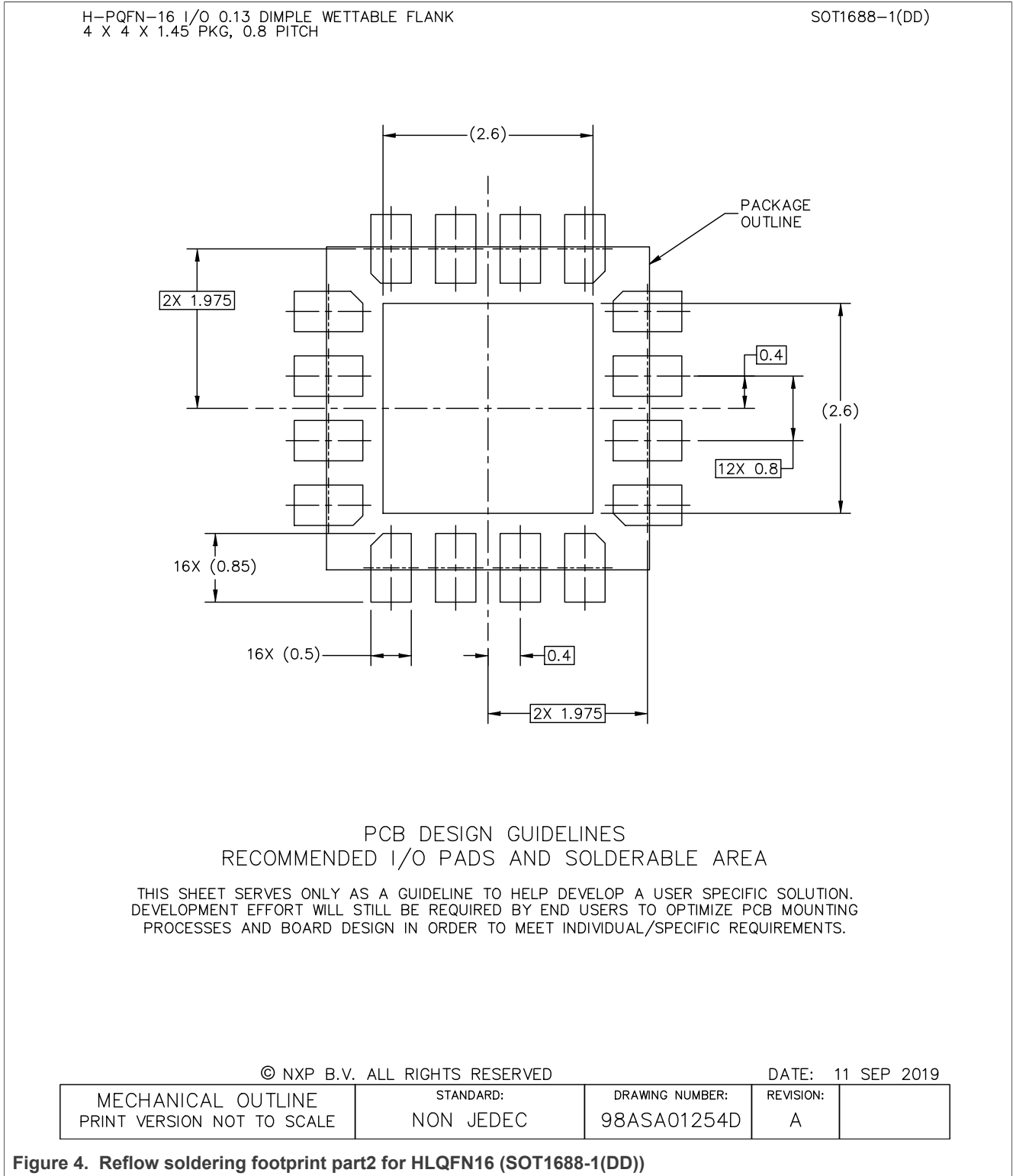
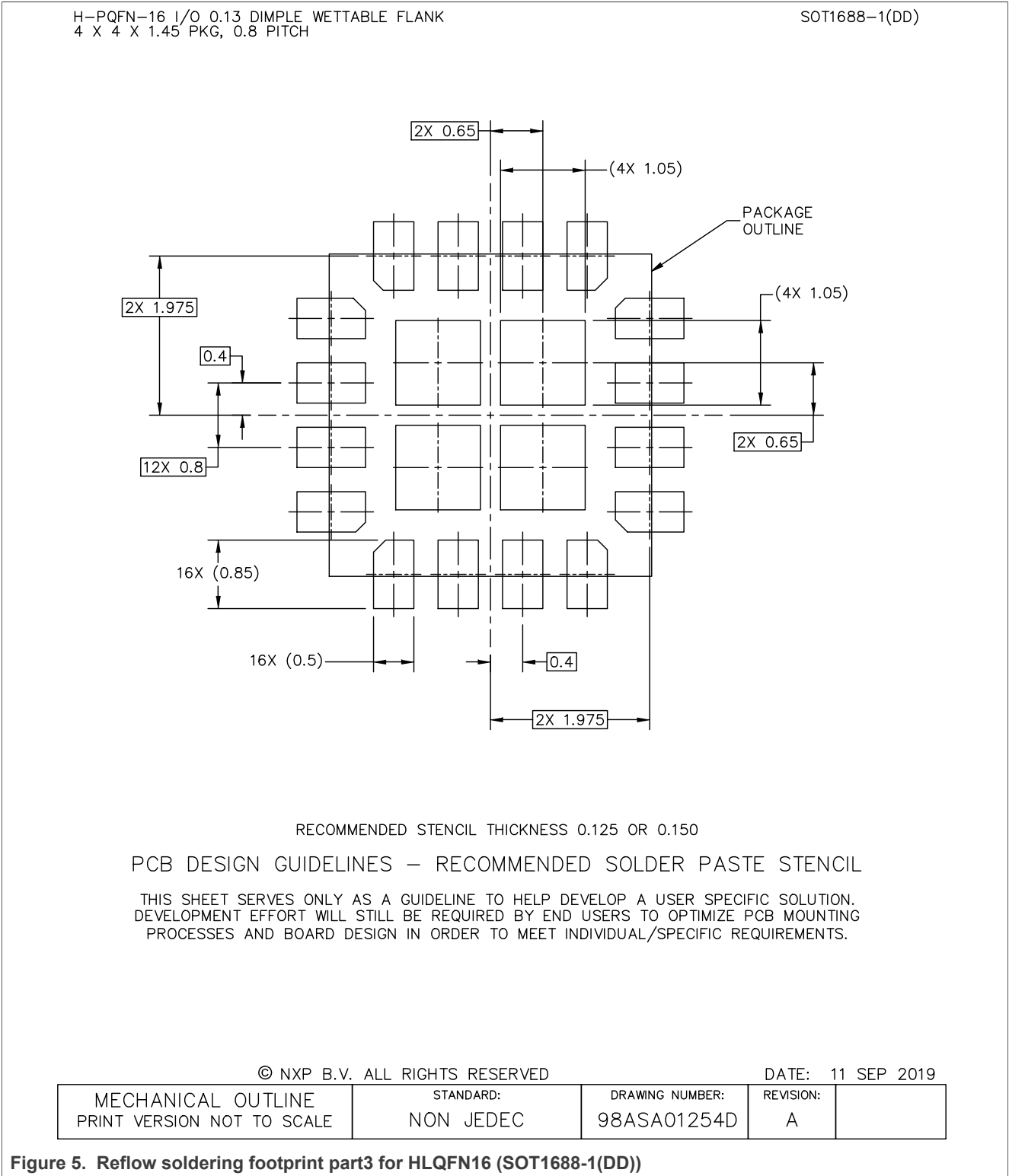
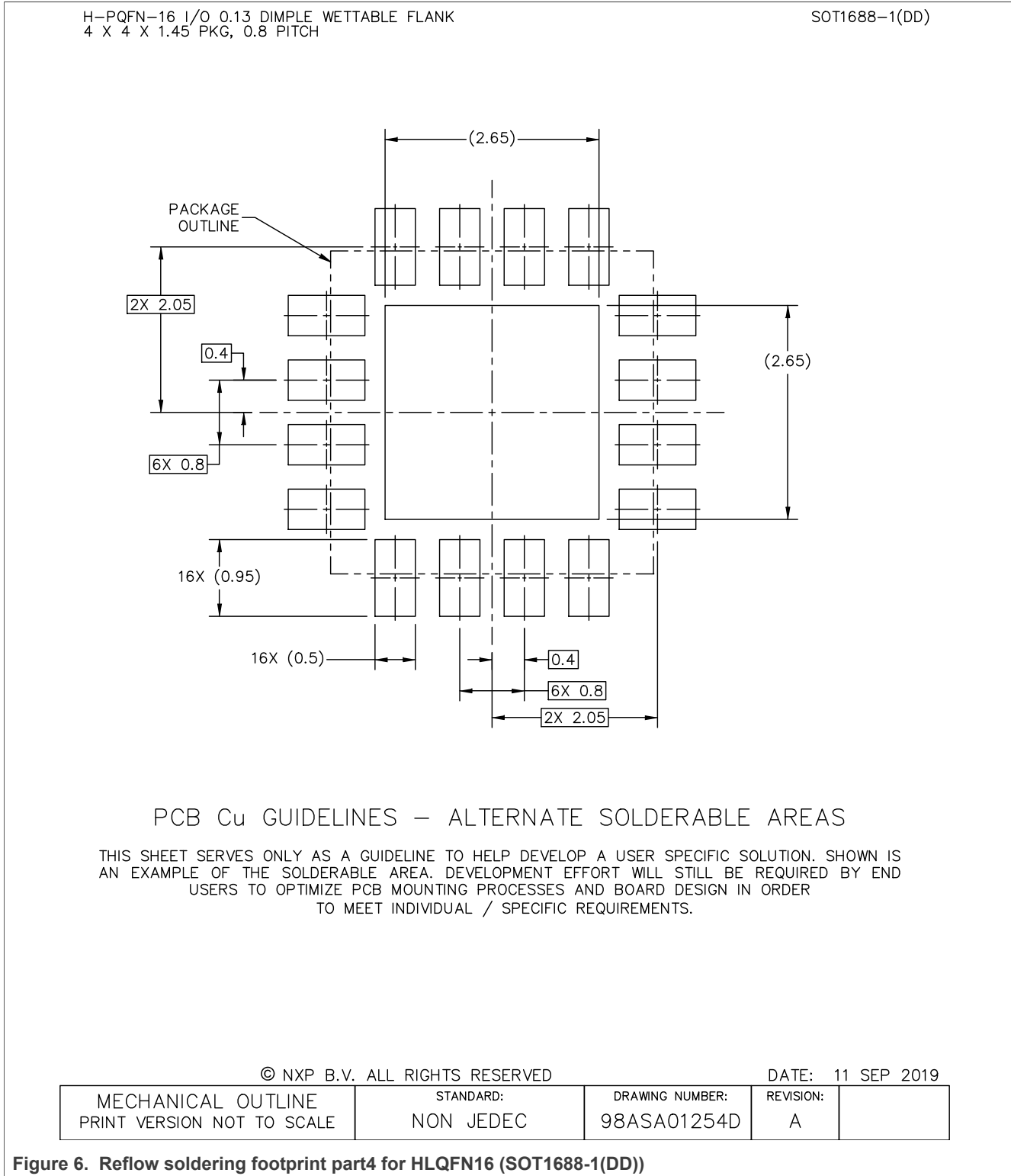


Figure 4. Reflow soldering footprint part2 for HLQFN16 (SOT1688-1(DD))

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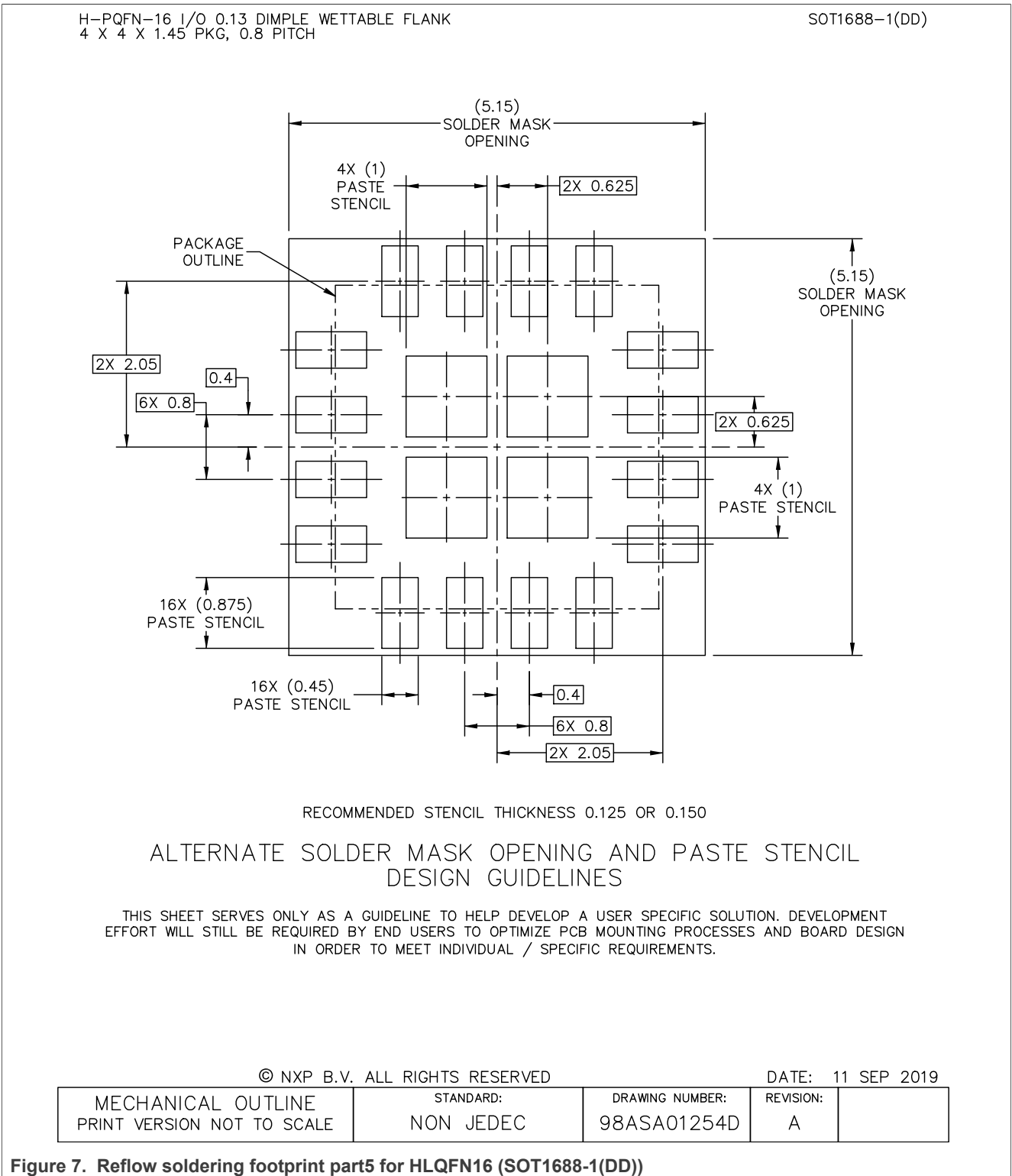


Figure 7. Reflow soldering footprint part5 for HLQFN16 (SOT1688-1(DD))



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H-PQFN-16 I/O 0.13 DIMPLE WETTABLE FLANK  
4 X 4 X 1.45 PKG, 0.8 PITCH

SOT1688-1(DD)

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.25 MM.
6. RECOMMENDED STENCIL AND SOLDER PASTED AREA ARE IN SHEET 3 TO 5.

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DATE: 11 SEP 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01254D	REVISION: A	
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Figure 8. Package outline note HLQFN16 (sot1688-1(DD))

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## 4 Legal information

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